



ASMCC0130

SOT-363

Min

0.10

Max

0.30

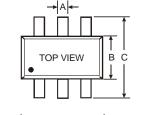
APPLICATION SPECIFIC MULTI-CHIP CIRCUIT

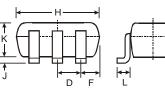
Features

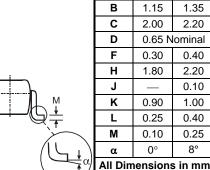
- **Epitaxial Planar Die Construction**
- Lead Free By Design/RoHS Compliant (Note 1)
- "Green" Device (Note 2)

Mechanical Data

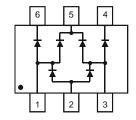
- Case: SOT-363
- Case Material: Molded Plastic. "Green" Molding Compound. UL Flammability Classification Rating 94V-0
- Moisture Sensitivity: Level 1 per J-STD-020C
- Terminal Connections: See Diagram
- Terminals: Finish Matte Tin. Solderable per MIL-STD-202, Method 208
- Marking Information: See Page 3
- Ordering Information: See Page 3
- Weight: 0.006 grams (approximate)

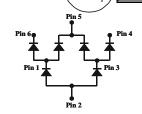






Dim





Maximum Ratings, Diode Element (BAT54) @T_A = 25°C unless otherwise specified

Characteristic		Symbol	Value	Unit	
Peak Repetitive Reverse Voltage Working Peak Reverse Voltage DC Blocking Voltage		V _{RRM} V _{RWM} V _R	30	V	
Forward Continuous Current	(Note 4)	l _F	200	mA	
Repetitive Peak Forward Current		I _{FRM}	300	mA	
Forward Surge Current @ t < 1.0s		I _{FSM}	600	mA	
Power Dissipation	(Note 4)	Pd	200	mW	
Thermal Resistance, Junction to Ambient Air	(Note 4)	$R_{ hetaJA}$	625	°C/W	
Operating and Storage Temperature Range		T _j , T _{STG}	-65 to +125	°C	

Electrical Characteristics, Diode Element (BAT54) @TA = 25°C unless otherwise specified

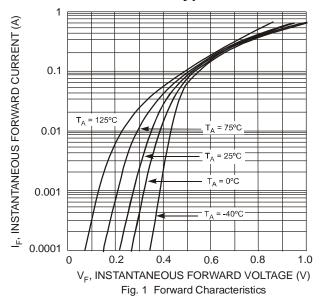
Characteristic		Symbol	Min	Тур	Max	Unit	Test Condition
Reverse Breakdown Voltage	(Note 3)	$V_{(BR)R}$	30	_	_	V	$I_R = 100 \mu A$
Forward Voltage	(Note 3)	VF	_		240 320 400 500 1000		$\begin{split} I_F &= 0.1 \text{mA} \\ I_F &= 1 \text{mA} \\ I_F &= 10 \text{mA} \\ I_F &= 30 \text{mA} \\ I_F &= 100 \text{mA} \end{split}$
Reverse Leakage Current	(Note 3)	I _R		_	2.0	μА	V _R = 25V
Total Capacitance		C _T	_	_	10	pF	V _R = 1.0V, f = 1.0MHz
Reverse Recovery Time		t _{rr}	_	_	5.0	ns	I_F = 10mA through I_R = 10mA to I_R = 1.0mA, R_L = 100 Ω

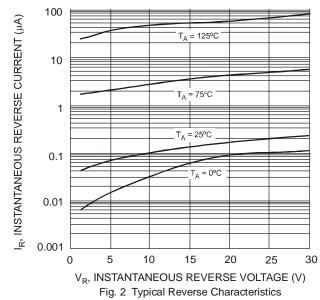
Notes:

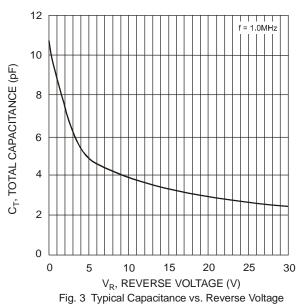
- 1. No purposefully added lead.
- 2. Diodes Inc.'s "Green" policy can be found on our website at http://www.diodes.com/products/lead_free/index.php.
- Short duration pulse test used to minimize self-heating effect.
- 4. Part mounted on FR-4 PC board with recommended pad layout, which can be found on our website at http://www.diodes.com/datasheets/ap02001.pdf.

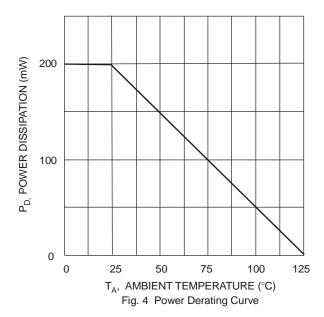


Typical Characteristics - Per Diode Element









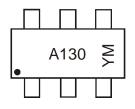


Ordering Information (Note 5)

Device	Packaging	Shipping		
ASMCC0130-7	SOT-363	3000/Tape & Reel		

Notes: 5. For packaging details, go to our website at http://www.diodes.com/datasheets/ap02007.pdf.

Marking Information



A130 = Product Type Marking Code (See Page 1) YM = Date Code Marking Y = Year ex: S = 2005 M = Month ex: 9 = September

Date Code Key

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Year	2005	2006	2007	2008	2009	2010	2011	2012	
Code	S	Т	U	V	W	Х	Υ	Z	

	Month	Jan	Feb	Mar	Apr	May	Jun	Jul	Aug	Sep	Oct	Nov	Dec
Ì	Code	1	2	3	4	5	6	7	8	9	0	N	D

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